MEMORY
DataFlash®
Serial DataFlash

Part Number	Density (Mbits)	VCC Min (V)	Interface Architecture	Speed (MHz)	SRAM/Buffers	Sector Lockdown	Serial Number	Packages	Availability
Page-Erase, Byte-Alterable, 2.7 to 3.6V – Commercial/Industrial Temperature Grades									
AT45DB011B	1	2.7	Serial (SPI Bus)	20	1 (264 Bytes)			*C*(9C1)-*S*(8S2)-*X*(14X)	Now
AT45DB011D	1	2.7	Serial (SPI Bus)	66	1 (256/264 Bytes)	•	•	*S*(8S2)-*SS*(8S1)-*M*(8M1-A)	2Q2007
AT45DB021B	2	2.7	Serial (SPI Bus)	20	2 (264 Bytes Each)			*C*(9C1)-*S*(8S2)-*T*(28T)-*R*(28R)	Now
AT45DB021D	2	2.7	Serial (SPI Bus)	66	1 (256/264 Bytes)	•	•	*S*(8S2)-*SS*(8S1)-*M*(8M1-A)	1Q2007
AT45DB041D	4	2.7	Serial (SPI Bus)	66	2 (256/264 Bytes Each)	•	•	*S*(8S2)-*SS*(8S1)-*M*(8M1-A)	Now
AT45DB081B	8	2.7	Serial (SPI Bus)	20	2 (264 Bytes Each)			*C*(14C1)-*CN*(8CN3)-*T*(28T)-*R*(28R)	Now
AT45DB081D	8	2.7	Serial (SPI Bus)	66	2 (256/264 Bytes Each)	•	•	*S*(8S2)-*SS*(8S1)-*M*(8M1-A)	1Q2007
AT45DB161D	16	2.7	Serial (SPI Bus)	66	2 (512/528 Bytes Each)	•	•	*S*(8S2)-*M*(8M1-A)-*T*(28T)	Now
AT45DB321D	32	2.7	Serial (SPI Bus)	66	2 (512/528 Bytes Each)	•	•	*S*(8S2)-*MW*(8MW)-*M*(8M1-A)-*T*(28T)	Now
AT45DB642D	64	2.7	Dual, SPI, Rapid8®	66/50	2 (1024/1056 Bytes Each)	•	•	*CN*(8CN3)-*T*(28T)	Now
Page-Erase, Byte-Alterable, Low Battery Voltage, 2.5 to 3.6V – Commercial/Industrial Temperature Grades									
AT45DB041D-2.5	4	2.5	Serial (SPI Bus)	50	2 (256/264 Bytes Each)	•	•	*S*(8S2)-*SS*(8S1)-*M*(8M1-A)	Now
AT45DB081B-2.5	8	2.5	Serial (SPI Bus)	15	2 (264 Bytes Each)			*C*(14C1)-*CN*(8CN3)-*T*(28T)-*R*(28R)	Now
AT45DB081D-2.5	8	2.5	Serial (SPI Bus)	50	2 (256/264 Bytes Each)	•	•	*S*(8S2)-*SS*(8S1)-*M*(8M1-A)	1Q2007
AT45DB161D-2.5	16	2.5	Serial (SPI Bus)	50	2 (512/528 Bytes Each)	•	•	*S*(8S2)-*M*(8M1-A)-*T*(28T)	Now

DataFlash Cards

Part Number	Density (Mbytes)	VCC Min (V)	Interface Architecture	Speed (MHz)	SRAM/Buffers	Sector Lockdown	Serial Number	Packages	Availability
Page-Erase, Byte-Alterable, 2.7 to 3.6V – Industrial Temperature Grades									
AT45DCB002D	2	2.7	Serial (SPI Bus)	66	2 (528 Bytes Each)	•	•	7DF1	Now
AT45DCB004D	4	2.7	Serial (SPI Bus)	66	2 (528 Bytes Each)	•	•	7DF1	Now
AT45DCB008D	8	2.7	Serial (SPI Bus)	66	2 (1056 Bytes Each)	•	•	7DF1	Now

Serial Firmware DataFlash

Part Number	Density (Mbits)	VCC Min (V)	Interface Architecture	Speed (MHz)	SRAM/Buffers	Sector Lockdown	Serial Number	Packages	Availability
Uniform Block Erase Serial Flash, 2.7 to 3.6 – Industrial Temperature Grades									
AT26F004	4	2.7	Serial (SPI Bus)	33				*S*(8S2)-*SS*(8S1)-*M*(8M1-A)	Now
AT26DF081A	8	2.7	Serial (SPI Bus)	70				*S*(8S2)-*SS*(8S1)	Now
AT26DF161	16	2.7	Serial (SPI Bus)	66				*S*(8S2)-*M*(8M1-A)	Now
AT26DF161A	16	2.7	Serial (SPI Bus)	70				*S*(8S2)-*SS*(8S1)-*M*(8M1-A)	1Q2007
AT26DF321	32	2.7	Serial (SPI Bus)	66				*S*(8S2)-*S3*(16S2)	Now

Notes: 1.   Package Designator:
    C – CBGA: **9C1**, 9-ball, 5 x 5 x 1.2 mm; **14C1**, 14-ball, 4.5 x 7 x 1.4 mm; **24C3**, 24-ball, 6 x 8 x 1.2 mm (Not Recommended for New Designs).
    CN – CASON: **8CN3**, 8-pad, 6 x 8 mm (Footprint Compatible with 8-pin SOIC, EIAJ).
    M, MW – MLF: **8M1-A**, 8-pad, 5 x 6 mm (Footprint Compatible to 8-pin SOIC, JEDEC); **8MW**, 8-pad, 6 x 8 mm (Footprint Compatible to 8-pin EIAJ SOIC).
    R – SOIC: **28R**, 28-lead, 0.330 Wide(Not Recommended for New Designs).
    SS – SOIC (Narrow): **8S1**, 8-lead, 0.150 Wide .
    S – SOIC: **8S2**, 8-lead, 0.209 Wide.
    S3 – SOIC: **16S2**, 16-lead, 0.300" Wide Body.
    T – TSOP (Type 1): **28T**, 28-lead, 8 x 13.4 mm.
    X – TSSOP: **14X**, 14-lead, 4.4 mm Body
    7DF1 – 7-pad, 2.5 mm Pitch, 24 x 32 x 1.4 mm Body DataFlash Card
   2.   *Green (RoHS Compliance)* Packaging Available for All DataFlash Products.